1. A carrier that is made of a composite material including fibers and a resin material and has a holding hole for holding a disk-shaped substrate when main surfaces of the substrate are polished or ground, wherein:

an inner circumferential wall surface of the holding hole has a plurality of recessed portions formed in a predetermined region that ~~extend~~ extends in a surface direction of the carrier orthogonal to the inner circumferential wall surface toward the outside of the holding hole to a certain depth and the plurality of recessed portions do not include fibers,

the plurality of recess portions are formed by removing the fibers exposed from the inner circumferential wall surface to the certain depth, and

the plurality of recessed portions are filled with a resin so as to block at least an entrance to the recessed portions.

2. A carrier that is made of a composite material including fibers and a resin material and has a holding hole for holding a disk-shaped substrate when main surfaces of the substrate are polished or ground, wherein:

an inner circumferential wall surface of the holding hole has a plurality of recessed portions,

the plurality of recessed portions are formed by removing the fibers exposed from the inner circumferential wall surface,

the plurality of recessed portions extend in a surface direction of the carrier orthogonal to the inner circumferential wall surface toward the outside of the holding hole and have concave shapes when they was regarded as a section, and

the plurality of recessed portions are filled with a resin so as to block at least an entrance to the recessed portions.

~~2~~ 3. The carrier according to claim 1 or 2, wherein the resin with which the plurality of recessed portions are filled is a resin having a lower hardness than that of the resin material included in the composite material.

~~3~~ 4. The carrier according to ~~claim 1 or 2~~ any of claims 1 to 3, wherein the resin with which the plurality of recessed portions are filled is a thermoplastic resin.

4 5. The carrier according to any of claims 1 to ~~3~~ 4, wherein, with regard to a roughness of a surface of the inner circumferential wall surface of the holding hole, Ra is 1.0 μm or less.

~~5~~ 6. The carrier according to any of claims 1 to 4 5, wherein a length, in the surface direction of the carrier, of ~~a~~ the predetermined region ~~including the plurality of recessed portions filled with the resin~~ is 100 μm or less.

~~6~~ 7. The carrier according to any of claims 1 to ~~5~~ 6, wherein the resin with which the recessed portions are filled covers the inner circumferential wall surface of the holding hole.

~~7~~ 8. A method for manufacturing a magnetic disk substrate, comprising processing for processing main surfaces of a disk-shaped substrate by horizontally holding the disk-shaped substrate in the holding hole of the carrier according to any of claims 1 to ~~6~~ 7, pressing processing surfaces of surface plates against the main surfaces of the disk-shaped substrate, and moving the processing surfaces of the surface plates and the disk-shaped substrate relative to each other.

~~8~~ 9. The method for manufacturing a magnetic-disk substrate according to claim ~~7~~ 8, wherein the processing is polishing processing for supplying a polishing liquid containing polishing abrasive particles between polishing pads that are attached to surfaces of the surface plates and the main surfaces of the disk-shaped substrate, and polishing the main surfaces of the disk-shaped substrate.

~~9~~ 10. The method for manufacturing a magnetic-disk substrate according to claim ~~7~~ 8, wherein the processing is grinding processing for grinding the main surfaces of the disk-shaped substrate with surface plates to which fixed abrasive particles are attached.

~~10~~ 11. The method for manufacturing a magnetic-disk substrate according to any of claims ~~7 to 9~~ 8 to 10, wherein a difference between a hole diameter of the holding hole and an outer diameter of the disk-shaped substrate is in a range of 0.1 to 1.0 mm.

~~11~~ 12. The method for manufacturing a magnetic-disk substrate according to any of claims ~~7 to 10~~ 8 to 11, wherein the substrate is a glass substrate.

~~12~~ 13. A method for manufacturing a magnetic disk, in which at least a magnetic recording layer is formed on a magnetic-disk substrate that is obtained with the manufacturing method according to any of claims ~~7 to 11~~ 8 to 12.